

低介电导热垫片/薄膜

THERMAL PAD/FILM

LOW-K SERIES

产品介绍 PRODUCT INTRODUCTION

低介电导热垫片系列具有低介电特性，在使用过程中减少信号传输的响应时间，从而保证信号接收和传输的顺利进行。

Low-K thermal pad series has low dielectric characteristics, which reduces the response time of signal transmission in the process of use, so as to ensure the smooth progress of signal reception and transmission.

产品特点 PRODUCT FEATURE

- 低介电常数
- Low dielectric constant
- 柔软,可压缩性好
- Soft and compressible
- 适合通信应用
- Suitable for communication applications

典型应用 TYPICAL APPLICATION

- 通信设备
- Communication equipment
- 网络信息设备
- Network information equipment
- 交互式接收设备
- Interactive receiving device
- 航空电子
- Avionics
- 射频放大器
- RF amplifier

产品参数 PRODUCT PARAMETER

产品型号 Models	厚度 Thickness	导热系数 Thermal Conductivity	密度 Specific Gravity	硬度 Hardness	介电常数 Dielectric Constant	体积电阻率 Volume Resistivity	使用温度 Application Temperature	阻燃等级 Flammability Rating	保质期 Shelf Life
	mm	W/m. K	g/cm ³	shore oo	@10MHz	Ω • cm	℃	UL-94	month
STP 150 LK	0.5~10	1.5	1.4	35	3.0	10 ¹⁵	-40~150	VO	12
STP 250 LK	0.8~5.0	2.5	1.3	55	3.2	-	-40~150	HB	12
STP 600 LK	0.02~0.2	60(X-Y)	1.7	-	≤4.0(@1MHZ)	10 ¹³	-40~120	-	12